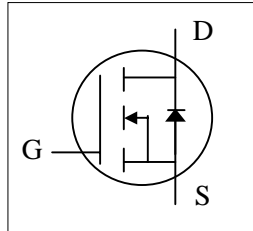




- ▼ 100% Avalanche Test
- ▼ Fast Switching Characteristics
- ▼ Simple Drive Requirement
- ▼ RoHS Compliant

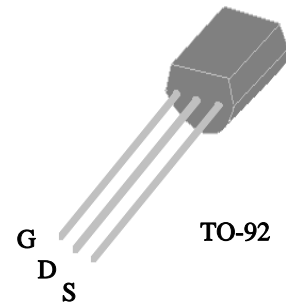


BV_{DSS}	600V
$R_{DS(ON)}$	5 Ω
I_D	400mA

Description

Advanced Power MOSFETs utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The TO-92 package is widely used for commercial-industrial applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	600	V
V_{GS}	Gate-Source Voltage	+30	V
$I_D@T_L=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	400	mA
I_{DM}	Pulsed Drain Current ¹	3	A
$P_D@T_L=25^\circ C$	Total Power Dissipation	2	W
	Linear Derating Factor	0.017	W/ $^\circ C$
E_{AS}	Single Pulse Avalanche Energy ²	20	mJ
I_{AR}	Avalanche Current	2	A
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Unit
Rthj-a	Maximum Thermal Resistance, Junction-ambient	150	$^\circ C/W$
Rthj-l	Maximum Thermal Resistance, Junction-lead	60	$^\circ C/W$



Electrical Characteristics @ $T_j=25^{\circ}\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=1mA$	600	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance ³	$V_{GS}=10V, I_D=400mA$	-	-	5	Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	2	-	4	V
g_{fs}	Forward Transconductance	$V_{DS}=10V, I_D=400mA$	-	570	-	mS
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=600V, V_{GS}=0V$	-	-	100	μA
I_{GSS}	Gate-Source Leakage	$V_{GS}=\pm 30V$	-	-	± 1	μA
Q_g	Total Gate Charge ³	$I_D=2A$	-	12	19	nC
Q_{gs}	Gate-Source Charge	$V_{DS}=480V$	-	2	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{GS}=10V$	-	5.5	-	nC
$t_{d(on)}$	Turn-on Delay Time ³	$V_{DD}=200V$	-	10	-	ns
t_r	Rise Time	$I_D=1A$	-	12	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=50\Omega, V_{GS}=10V$	-	52	-	ns
t_f	Fall Time	$R_D=200\Omega$	-	19	-	ns
C_{iss}	Input Capacitance	$V_{GS}=0V$	-	375	600	pF
C_{oss}	Output Capacitance	$V_{DS}=10V$	-	170	-	pF
C_{riss}	Reverse Transfer Capacitance	$f=1.0MHz$	-	45	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ³	$T_j=25^{\circ}\text{C}, I_S=2A, V_{GS}=0V$	-	-	1.5	V
t_{rr}	Reverse Recovery Time ³	$I_S=2A, V_{GS}=0V,$	-	340	-	ns
Q_{rr}	Reverse Recovery Charge	$dI/dt=100A/\mu s$	-	2.2	-	μC

Notes:

1. Pulse width limited by Max. junction temperature.
2. Starting $T_j=25^{\circ}\text{C}$, $V_{DD}=50V$, $L=10mH$, $R_G=25\Omega$
3. Pulse test

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

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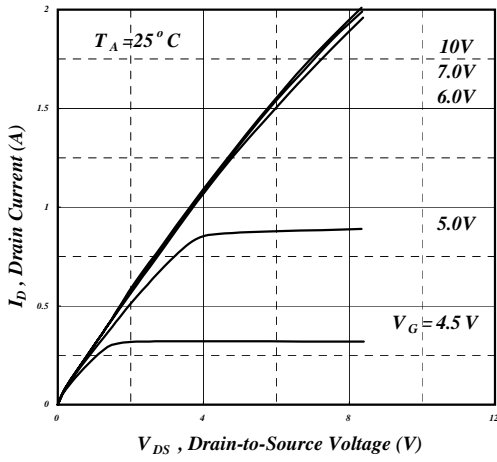


Fig 1. Typical Output Characteristics

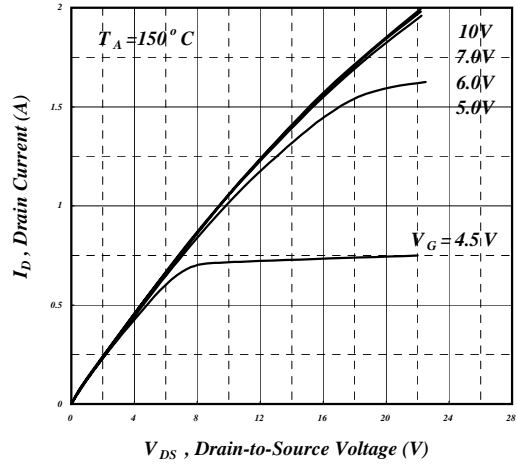


Fig 2. Typical Output Characteristics

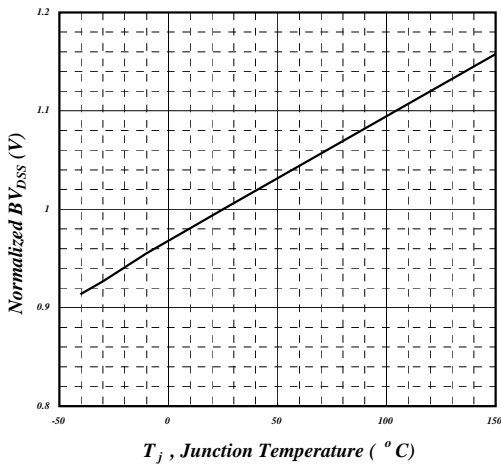


Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

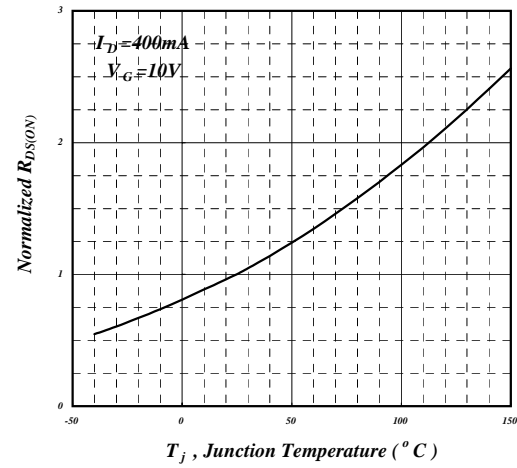


Fig 4. Normalized On-Resistance v.s. Junction Temperature

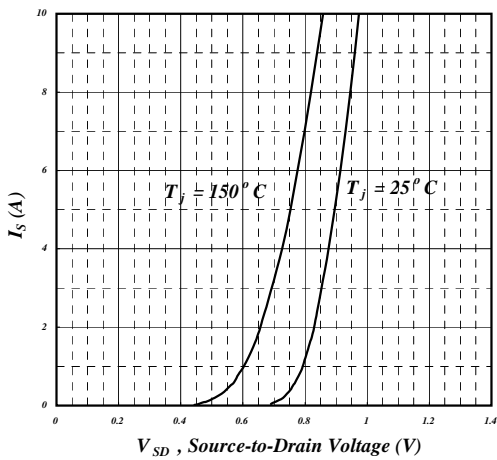


Fig 5. Forward Characteristic of Reverse Diode

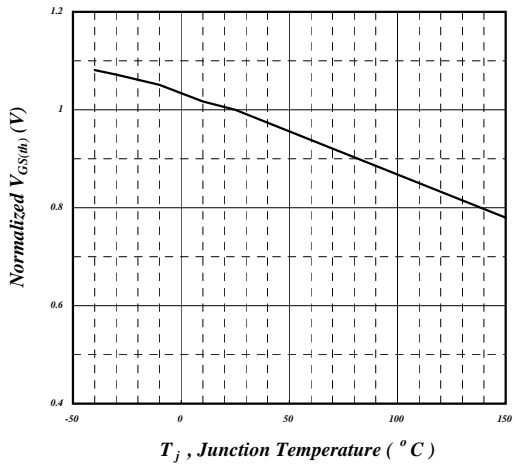


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

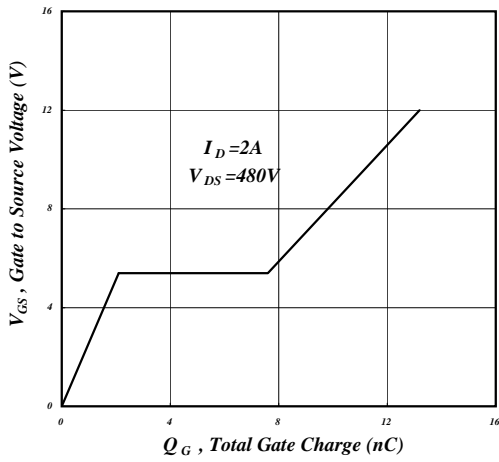


Fig 7. Gate Charge Characteristics

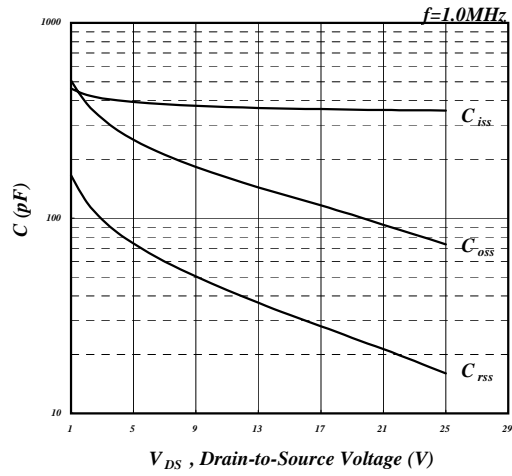


Fig 8. Typical Capacitance Characteristics

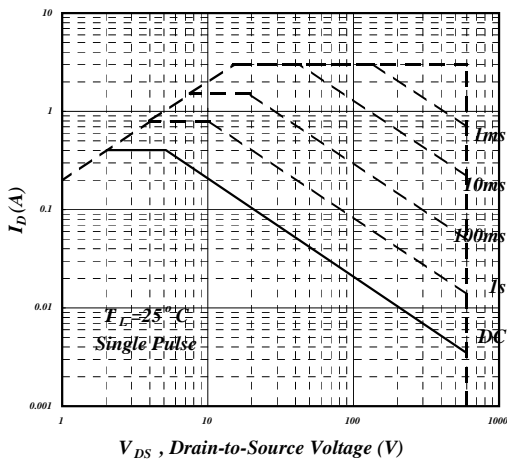


Fig 9. Maximum Safe Operating Area

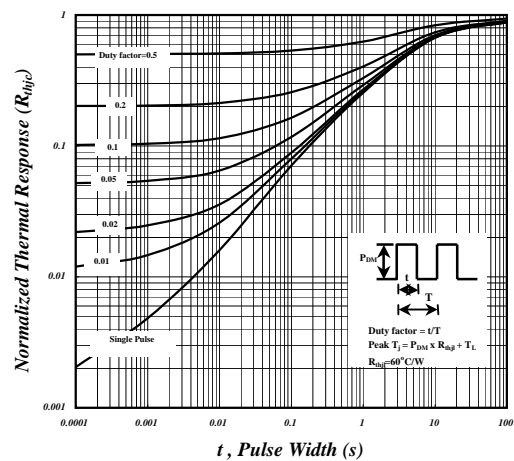


Fig 10. Effective Transient Thermal Impedance

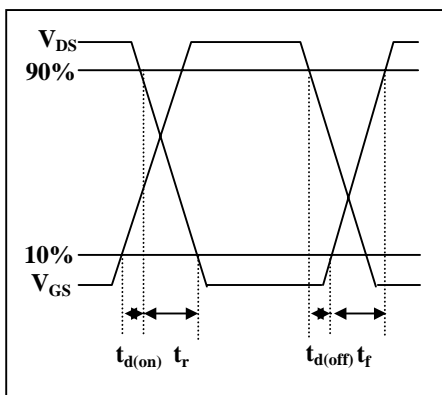


Fig 11. Switching Time Waveform

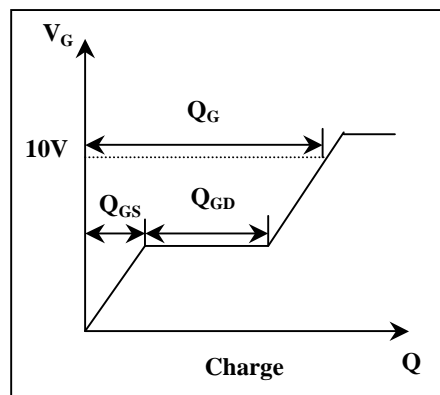


Fig 12. Gate Charge Waveform